



Product Change Notification: CBOL-04GUQH155

Date:

17-Jun-2026

Product Category:

Memory

Notification Subject:

CCB 7788.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 24CS64, 24CS32, 24AA64, 24FC64, 24LC32AF, 24LC64, 24AA32AF, 24LC32A, 24AA32A, 24AA64F, 24LC64F, 24FC64F, 24LC128, 24FC128, 24AA128, 24CS128, 24CS256, 24LC256, 24AA256, 24FC256, 24CS512, 24CSM01 and 25CSM01 device families available in 8L MSOP (3x3mm) package at MTAI assembly site.

Affected CPNs:

[CBOL-04GUQH155_Affected_CPN_06172026.pdf](#)

[CBOL-04GUQH155_Affected_CPN_06172026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for 24CS64, 24CS32, 24AA64, 24FC64, 24LC32AF, 24LC64, 24AA32AF, 24LC32A, 24AA32A, 24AA64F, 24LC64F, 24FC64F, 24LC128, 24FC128, 24AA128, 24CS128, 24CS256, 24LC256, 24AA256, 24FC256, 24CS512, 24CSM01 and 25CSM01 device families available in 8L MSOP (3x3mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
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Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No
Die Attach Material	8390A (PFAS-Free)	8390A (PFAS-Free)	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 14 September 2026 (date code: 2638)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	September 2026				
Work Week	23	24	25	26	27		36	37	38	39	40
Qual Report Availability			X								
Final PCN Issue Date			X								
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 17, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN CBOL-04GUQH155 Qual Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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